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•	Members of the Texas Instruments <i>Widebus</i> ™ Family Inputs Are TTL-Voltage Compatible	54ACT16952 WD PACKAGE 74ACT16952 DL PACKAGE (TOP VIEW)					
•	Noninverting Outputs			<u> </u>			
•	Two 16-Bit, Back-to-Back Registers Store Data Flowing in Both Directions	10EAB 1CLKAB 1CEAB		56 10EBA 55 1CLKBA 54 1CEBA			
•	Flow-Through Architecture Optimizes PCB Layout	GND 1A1	4	53 GND 52 1B1			
٠	Distributed V _{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise		7	51] 1B2 50] V _{CC}			
٠	<i>EPIC</i> [™] (Enhanced-Performance Implanted CMOS) 1-μm Process 500-mA Typical Latch-Up Immunity at 125°C	1A3 L 1A4 L	9	49] 1B3 48] 1B4			
٠		1A5 L GND [1A6 [11	47] 1B5 46] GND 45] 1B6			
•	Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using	1A7 [1A7 [1A8 [13	44] 1B7 43] 1B8			
	25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD)	2A1	15	42 2B1			
	Packages Using 25-mil Center-to-Center	2A2 2A3		41 2B2 40 2B3			
	Pin Spacings			39 GND			
dos	cription	2A4 [19	38] 2B4			
ucs	The 'ACT16952 are 16-bit registered transceivers	2A5 🛛		37 2 B5			
	that contain two sets of D-type flip-flops for	2A6 [36 2B6			
	temporary storage of data flowing in either	V _{CC} 2A7		35 V _{CC} 34 2B7			
	direction. They can be used as two 8-bit	248		33 288			

transceivers or one 16-bit transceiver. Data on the A or B bus is stored in registers on the low-to-high transition of the clock (CLKAB or CLKBA) input, provided that the clock-enable (CEAB or CEBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port. To avoid false clocking of the flip-flops, CEAB (or CEBA) should not be switched from low to high while CLKAB (or CLKBA) is low.

U			
2A4 🛛	19	38] 2B4
2A5 🛛	20	37	2B5
2A6 🛛	21	36	2B6
v _{cc} [22	35] v _{cc}
2A7 🛛	23	34] 2B7
2A8 🛛	24	33] 2B8
GND [25	32] GND
2CEAB	26	31	2CEBA
2CLKAB	27	30	2CLKBA
20EAB	28	29	20EBA

The 74ACT16952 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16952 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16952 is characterized for operation from -40°C to 85°C.



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54ACT16952, 74ACT16952 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCAS159C – JANUARY 1991 – REVISED APRIL 1996

FUNCTION TABLE[†]

	OUTPUT			
CEAB	CLKAB	OEAB	Α	В
н	Х	L	Х	в ₀ ‡ в ₀ ‡
Х	Н	L	Х	в ₀ ‡
L	\uparrow	L	L	L
L	\uparrow	L	Н	н
Х	Х	Н	Х	Z

A-to-B data flow is shown; B-to-A data flow is similar but uses CEBA, CLKBA, and OEBA.

‡Level of B before the indicated steady-state input conditions were established



logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16952			74ACT16952			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2	4	εh	2			V
VIL	Low-level input voltage		EL	0.8			0.8	V
VI	Input voltage	0	54	VCC	0		VCC	V
Vo	Output voltage	0	5	VCC	0		VCC	V
ЮН	High-level output current	4	20	-24			-24	mA
IOL	Low-level output current	A	,	24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
ТА	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	RAMETER	TEST CONDITIONS	V	Т	₄ = 25°C		54ACT	16952	74ACT16952		UNIT	
PARAMETER		TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
			4.5 V	4.4			4.4		4.4			
		I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4			
Varia		1	4.5 V	3.94			3.8		3.8		V	
Vон		I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8		v	
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V									
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85	2	3.85			
		L	4.5 V			0.1		0.1		0.1		
		I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1		
		1	4.5 V			0.36	K	0.44		0.44	V	
VOL		I _{OL} = 24 mA	5.5 V			0.36	20	0.44		0.44	v	
		I _{OL} = 50 mA [†]	5.5 V				0					
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V				4	1.65		1.65		
Ιį	Control inputs	$V_{I} = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA	
loz‡	A or B ports	$V_{O} = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	μA	
ICC		$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	5.5 V			8		80		80	μA	
∆I _{CC} §		One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA	
Ci	Control inputs	$V_I = V_{CC}$ or GND	5 V		3						pF	
Cio	A or B ports	$V_{O} = V_{CC}$ or GND	5 V		12						pF	

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] For I/O ports, the parameter IOZ includes the input leakage current.

§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$ (unless otherwise noted)

			T _A = 2	25°C	54ACT	16952	74ACT	16952	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	75	0	75	0	75	MHz	
tw	Pulse duration, CLK high or low	6.7		6.7	6	6.7		ns		
		Data	5		5	N. M	5			
t _{su}	Setup time before CLK [↑]	CEAB or CEBA	6.5		6.5		6.5		ns	
±.		Data	1		<u>`</u> ?1		1		ns	
th	Hold time after CLK↑	CEAB or CEBA	0		0		0			



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Т	T _A = 25°C			54ACT16952		74ACT16952	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}			75			75		75		MHz
^t PLH	CLK	A or P	4.7	8.5	10.7	4.7	11.8	4.7	11.8	ns
^t PHL	CLK	A or B	4.9	8.7	10.5	4.9	11.7	4.9	11.7	
^t PLH		A or B	4.7	8.5	10.7	4.7	11.8	4.7	11.8	ns
^t PHL	CEBA or CEAB		4.9	8.7	10.5	4.9	1 1.7	4.9	11.7	
^t PZH		A or D	3.4	8.1	10.2	3.4	11.2	3.4	11.2	
^t PZL	OEBA or OEAB	A or B	4.2	9.6	11.8	4.2	13	4.2	13	ns
^t PHZ		A or P	5.2	7.5	8.9	Q 5.2	9.4	5.2	9.4	
^t PLZ	OEBA or OEAB	A or B	4.5	6.7	8.2	4.5	8.7	4.5	8.7	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT	
Cpd	Power dissipation capacitance per transceiver	Outputs enabled	C _L = 50 pF,	f = 1 MHz	55	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	0	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
74ACT16952DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16952	Samples
74ACT16952DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16952	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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